

AS_BLEINTCONxxx FleX-BLE™ Flexible BLE Interposer Flexible Hybrid System

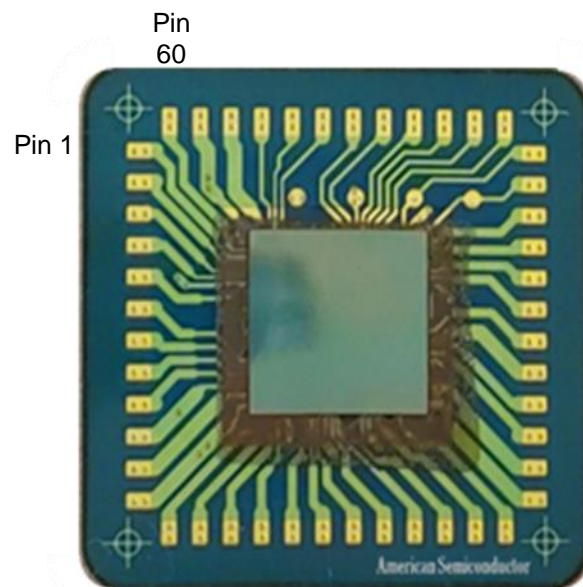


FleX-BLE Interposer

The AS_BLEINTCON is a Flexible Hybrid System composed of an AS_NRF51822P physically flexible FleX-BLE IC flip-chip mounted to a copper on polyimide interposer. The interposer provides a fanout function to support easier connection to the pins due to the larger pads and increased spacing between the pads. All pads are at the periphery of the interposer and have electrical connection points on both the top and bottom surfaces. The FleX-BLE IC on this interposer supports *Bluetooth*® Low Energy (BLE) communication. The American Semiconductor FleX™ Semiconductor-on-Polymer™ process is used to convert the standard CMOS product into the robust, thin and physically flexible form factor. This feature rich FleX-BLE product has an ARM® Cortex™ M0 processor, 256KB embedded Flash memory, 32KB RAM, encryption co-processor, temperature sensor, and 10-bit analog-to-digital converter. The FleX-BLE operates from 1.8-3.6V. More information on the FleX-BLE IC is available at <https://www.americansemi.com/flex-ics.html>.

FleX-BLE Interposer Physical Specifications

Size	11 x 11mm
Base Material	76um (3 mil) polyimide
Metallization	2 layers of 9um ENIG plated copper
Pad Count	60
Pad Width	0.3mm
Pad Spacing	0.3mm



FleX-BLE Interposer Ordering Information

Part Number	Description
AS_BLEINTCON.fhs	FleX-BLE interposer flexible hybrid system with ground plane under die and power and ground pins shorted on interposer
AS_BLEINTGP.fhs	FleX-BLE interposer flexible hybrid system with ground plane under die
AS_BLEINTNGP.fhs	FleX-BLE interposer flexible hybrid system without ground plane

AS_BLES02INTxxx FleX-BLE™

Flexible BLE Interposer Flexible Hybrid System



FleX-BLE Interposer Pin List

Pin	Description	Pin	Description	Pin	Description	Pin	Description
1	AVDD	16	VSS	31	No connect	51	P0.29
2	VSS	17	SWDIO/nRESET	32	P0.06 AIN7 AREF1	52	P0.28
3	VSS	18	P0.16	33	P0.05 AIN6	53	P0.27 AIN1 XL1
4	VSS	19	P0.15	34	P0.04 AIN5	54	P0.26 AIN0 XL2
5	VSS	20	P0.14	35	P0.03 AIN4	55	VSS
6	ANT2	21	P0.13	36	VSS	51	P0.25
7	ANT1	22	VSS	37	P0.02 AIN3	52	P0.24
8	VDD_PA	23	P0.12	38	P0.01 AIN2	53	P0.23
9	DEC2	24	P0.11	39	P0.00 AFEF0	54	VSS
10	VSS	25	P0.10	40	P0.31	55	P0.22
11	P0.20	26	P0.09	41	P0.30	56	P0.21
12	P0.19	27	P0.08	42	VSS	57	DEC1
13	P0.18	28	VSS	43	DCC	58	VSS
14	P0.17	29	VDD	44	VDD	59	XC2
15	SWDCLK	30	No connect	45	No connect	60	XC1

Preliminary Information

This product and the associated documentation are still in development. Changes to the design and specification may be expected.

Contact Info

For more information or to purchase FleX products, please contact us at:

Email: sales@americansemi.com

Phone: 208.336.2773

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